

**In Claims:**

Following is a list of all pending claims. Marked up versions of all revised claims, showing insertions and deletions, are included in Appendix A.

1. (Amended) A semiconductor package, comprising:  
a semiconductor die with a bond pad;  
a package lead;  
a bond wire comprising a first end portion coupled to the package lead, a second end portion coupled to the bond pad, and an intermediate portion; and  
an intermediate lead finger positioned between the package lead and the bond pad, wherein the intermediate lead finger is coupled to the intermediate portion of the bond wire, and remains so coupled through a subsequent molding process.
2. The package of claim 1, further comprising an intermediate lead finger mounting substrate, wherein the intermediate lead finger is mounted on the intermediate lead finger mounting substrate.
3. (Amended) The package of claim 2, wherein the intermediate lead finger and the intermediate lead finger mounting substrate are formed of a non-conducting material.
4. The package of claim 3, further comprising a die attachment pad attached to the intermediate lead finger mounting substrate.
5. The package of claim 4, wherein the die attachment pad is made of a heat-conducting material for rapid heat dissipation.
6. The package of claim 4, further comprising a mold compound that encloses the semiconductor die, a portion of the package lead, the bond wire, the intermediate lead finger, and the die attachment pad.
7. The package of claim 1, wherein the intermediate lead finger comprises a non-conducting portion for attaching to the intermediate portion of the bond wire.

8. The package of claim 1, wherein the semiconductor die comprises a programmable logic device.

9. (Amended) A semiconductor package, comprising:  
an intermediate lead finger mounting substrate having a first surface and a second surface;  
a semiconductor die with a bond pad, the semiconductor die being attached on the first surface of the intermediate lead finger mounting substrate;  
a package lead;  
a bond wire comprising a first end portion coupled to the package lead, a second end portion coupled to the bond pad, and an intermediate portion;  
an intermediate lead finger mounted on the first surface of the intermediate lead finger mounting substrate, wherein the intermediate lead finger is positioned between the package lead and the bond pad, and wherein the intermediate lead finger is attached to the intermediate portion of the bond wire, and remains so attached through a subsequent molding process;  
a heat sink coupled to the second surface of the intermediate lead finger mounting substrate; and  
a mold compound that encloses the semiconductor die, a portion of the package lead, the bond wire, the intermediate lead finger, and the heat sink.

10. The package of claim 9, wherein the intermediate lead finger and the intermediate lead finger mounting substrate are formed of a non-conducting material.

11. The package of claim 9, wherein the intermediate lead finger comprises a non-conducting portion for attaching to the intermediate portion of the bond wire.

12. The package of claim 9, wherein the semiconductor die comprises a programmable logic device.

13. The package of claim 9, wherein the semiconductor die is mounted on a center portion of the first surface of the intermediate lead finger mounting substrate, and wherein the intermediate lead finger is mounted on a peripheral portion of the first surface of the intermediate lead finger mounting substrate.

20. (Amended) A semiconductor package, comprising:  
a semiconductor die with a bond pad;  
a package lead;  
a bond wire comprising a first end portion coupled to the package lead, a second end portion coupled to the bond pad, and an intermediate portion; and  
an intermediate lead finger positioned between the package lead and the bond pad, the intermediate lead finger affixing at least part of the intermediate portion of the bond wire at a position between the semiconductor die and the package lead, and remains so affixed through a subsequent molding process.

21. The package of claim 20, further comprising an intermediate lead finger mounting substrate, wherein the intermediate lead finger is mounted on the intermediate lead finger mounting substrate.

22. (Amended) The package of claim 21, wherein the intermediate lead finger and the intermediate lead finger mounting substrate are formed of a non conducting material.

23. The package of claim 22, further comprising a die attachment pad attached to the intermediate lead finger mounting substrate.

24. The package of claim 23, wherein the die attachment pad is made of a heat conducting material for rapid heat dissipation.

25. The package of claim 23, further comprising a mold compound that encloses the semiconductor die, a portion of the package lead, the bond wire, the intermediate lead finger, and the die attachment pad.

26. The package of claim 20, wherein the intermediate lead finger comprises a non conducting portion for attaching to the intermediate portion of the bond wire.

27. The package of claim 20, wherein the semiconductor die comprises a programmable logic device.